



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of "Quality Parts,Customers Priority,Honest Operation,and Considerate Service",our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



## Contact us

Tel: +86-755-8981 8866 Fax: +86-755-8427 6832

Email & Skype: info@chipsmall.com Web: www.chipsmall.com

Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China



**NOTES :**

**1- MATERIAL:**

-HOUSING: LCP FIBER GLASS FILLED UL 94-V0, COLOR BLACK.

-TERMINAL: PHOSPHOR BRONZE

**PLATING :**

BASE FINISH: NICKEL

CONTACT SURFACE FINISH:

GOLD,

OR

GOLD FLASH OVER PALLADIUM NICKEL.

EXCEEDS PRODUCT REQUIREMENTS BASED ON PS-85506-001

2- JACK FOR MATING WITH IEC 60603-7 AND TIA-1096-A (90075 MOLEX SERIES).

3- PRODUCT SPECIFICATION PS-85506-001

4- PACKAGING SPECIFICATION PK-95022 (TRAY PACKAGING).

5- EXCEEDS CATEGORY 5E PERFORMANCE.

6- PC BOARD THICKNESS: 1.57

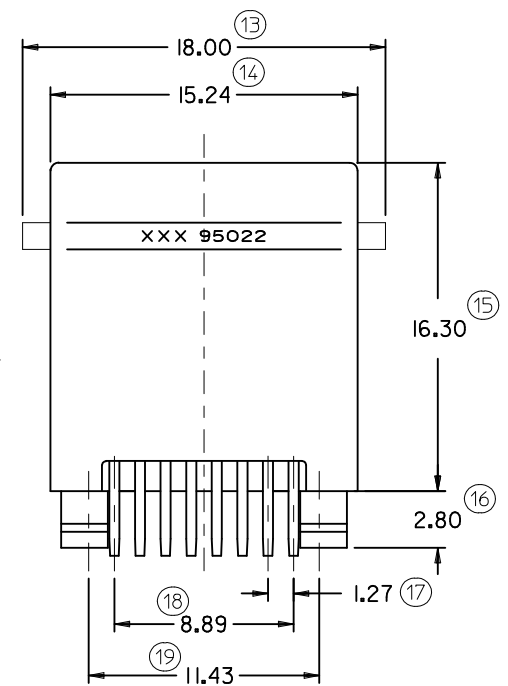
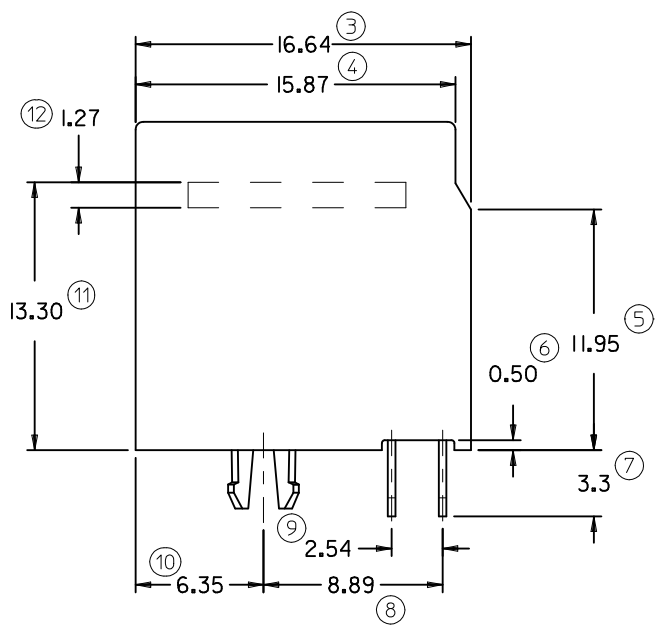
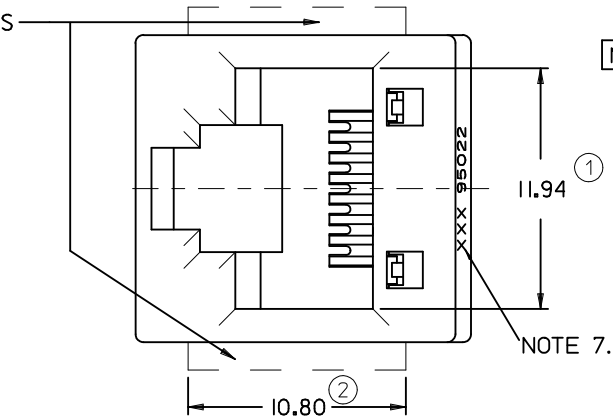
7- MANUFACTURING I.D. CAN BE MG, MXF OR MXI.

8- APPLICATION SPECIFICATION: AS-85513-001

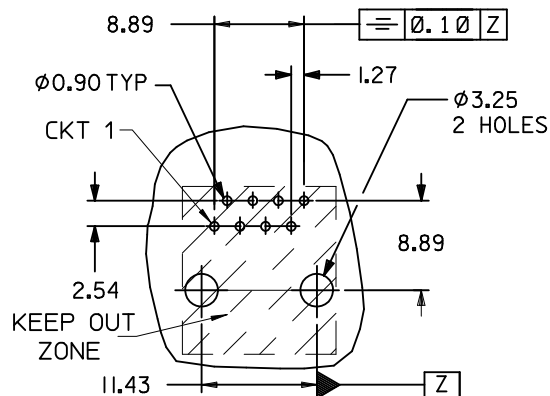
LAST INSPECTION NUMBER: 19

	JACK WITH RIBS	JACK WITHOUT RIBS
MATERIAL No.	85506-5001	85506-5002

OPTIONAL RIBS



**P.C.B. MOUNTING PATTERN**  
(see from component side)  
ALL DIMENSIONS REF DIMENSIONS



SCALE 2:1

REMOVED PLATING OPTION EC NO: IPG2012-0620 DRWING: DBYRNES 2012/04/03 CHKD: MSHAHN 2012/04/17 APPR: EFOLAN 2012/06/28	QUALITY SYMBOLS	GENERAL TOLERANCES (UNLESS SPECIFIED)	DIMENSION STYLE	SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION	
	▽=0 ∇=0	mm INCH	MM ONLY	4:1	METRIC		
		4 PLACES ± --- ± --- 3 PLACES ± --- ± --- 2 PLACES ± 0.15 ± --- 1 PLACE ± 0.25 ± ---	DRAWN BY DATE FB 98/02/25	TITLE HIGH SPEED MODULAR JACK HIGH PROFILE TOP ENTRY THROUGH HOLE 8 CIRCUIT			
		ANGULAR ± 2 °	CHECKED BY DATE MF 1998/02/26	MATERIAL NO. DOCUMENT NO. SHEET NO. SD-85506-501 1 OF 1			

DRAFT WHERE APPLICABLE  
MUST REMAIN  
WITHIN DIMENSIONS

APPROVED BY DATE FB 1998/02/28	MATERIAL NO. SEE CHART
SIZE A3	

THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION